

# T-1(3mm) ROUND LED LAMP

Part Number: L-937GGD

Green

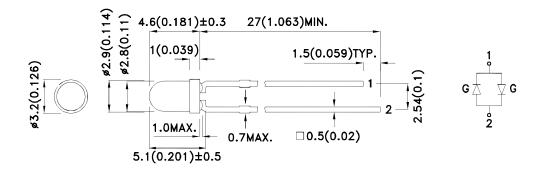
### **Features**

- Uniform light output.
- Low power consumption.
- Long life solid state reliability.
- RoHS compliant.

# Description

The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

## **Package Dimensions**



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is  $\pm 0.25(0.01")$  unless otherwise noted.
- Lead spacing is measured where the leads emerge from the package.
   The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

SPEC NO: DSAD0547 APPROVED: WYNEC

**REV NO: V.6 CHECKED: Allen Liu**  DATE: APR/15/2010 DRAWN: Z.Q.NI

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## **Selection Guide**

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
L-937GGD	Green (GaP)	GREEN DIFFUSED	4	15	- 60°
L-937 GGD	Green (GaP)	GREEN DIFFUSED	4	15	

- Notes: 1.  $\theta$ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. Luminous intensity/ luminous Flux: +/-15%.

## Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	565		nm	IF=20mA
λD [1]	Dominant Wavelength	Green	568		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Green	30		nm	IF=20mA
С	Capacitance	Green	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Green	2.2	2.5	V	Ir=20mA

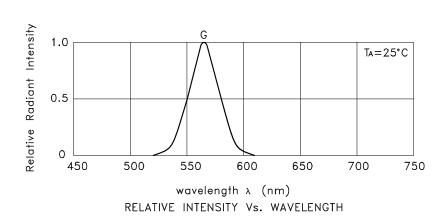
- 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

### Absolute Maximum Ratings at TA=25°C

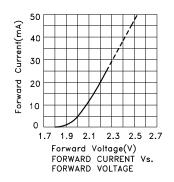
/ too oratio maximum realings at 171 20 0						
Parameter	Green	Units				
Power dissipation	62.5	mW				
DC Forward Current	25	mA				
Peak Forward Current [1]	140	mA				
Operating / Storage Temperature	-40°C To +85°C					
Lead Solder Temperature [2]	260°C For 3 Seconds	260°C For 3 Seconds				
Lead Solder Temperature [3]	260°C For 5 Seconds	260°C For 5 Seconds				

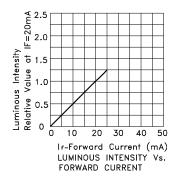
- Notes: 1. 1/10 Duty Cycle, 0.1ms Pulse Width. 2. 2mm below package base.
- 3. 5mm below package base.

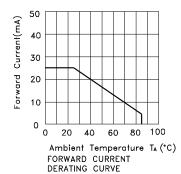
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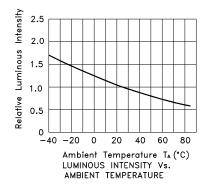


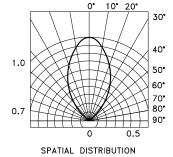
## L-937GGD Green





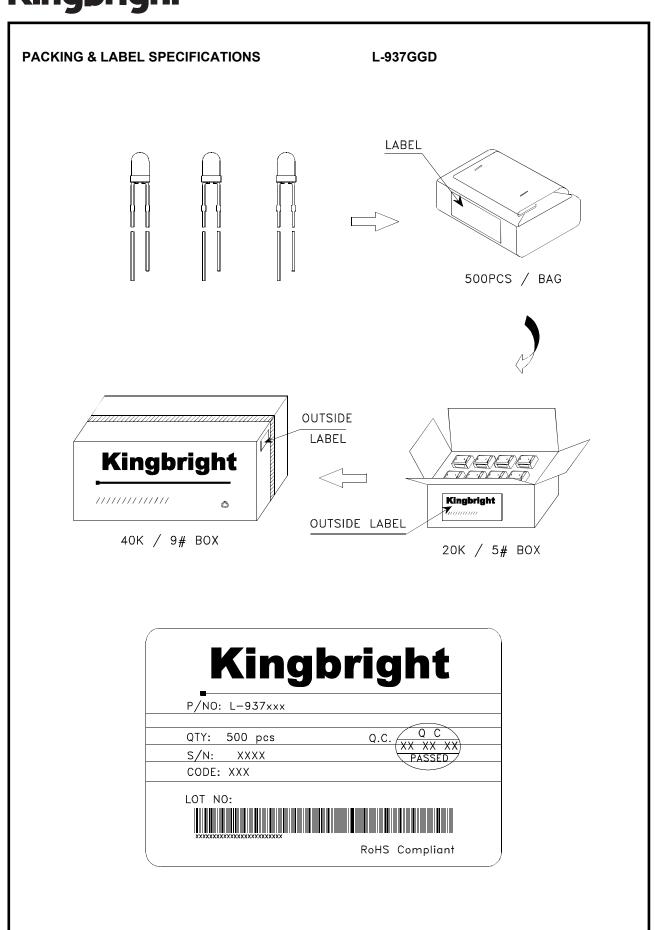






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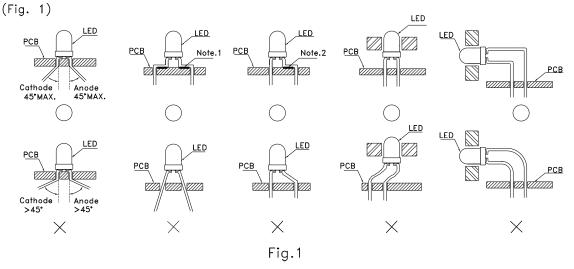
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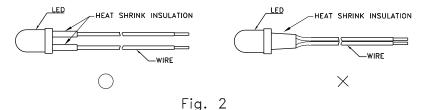
### LED MOUNTING METHOD

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead—forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.

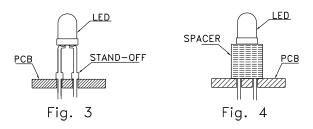


" $\bigcirc$ " Correct mounting method " $\times$ " Incorrect mounting method Note 1-2: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

2. When soldering wire to the LED, use individual heat—shrink tubing to insulate the exposed leads to prevent accidental contact short—circuit. (Fig. 2)



3. Use stand—offs (Fig. 3) or spacers (Fig. 4) to securely position the LED above the PCB.

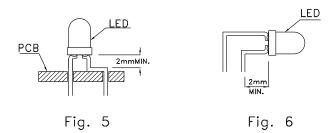


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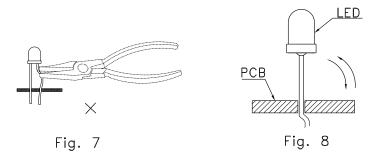
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## LEAD FORMING PROCEDURES

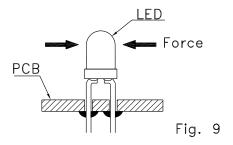
1. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)



- 2. Lead forming or bending must be performed before soldering, never during or after Soldering.
- 3. Do not stress the LED lens during lead—forming in order to fractures in the lens epoxy and damage the internal structures.
- 4. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)
- 5. Do not bend the leads more than twice. (Fig. 8)



6. After soldering or other high—temperature assembly, allow the LED to cool down to 50°C before applying outside force (Fig. 9). In general, avoid placing excess force on the LED to avoid damage. For any questions please consult with Kingbright representative for proper handling procedures.



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